



Company Contact:

Paul Prudhomme
SyChip, Inc.
972.202.8893
pprudhomme@sychip.com

Media Contact:

Jason Caldwell
Shelton
972.239.5119 x119
jcaldwell@sheltongroup.com

SyChip Announces Integrated Passive Device (IPD) Technology for the Mobile Handheld Market

Wireless innovator introduces the world's thinnest 802.11g plug-and-play module

Photo available for download at <http://www.sychip.com/products/WLAN-IPD-for-media.jpg>

PLANO, Texas (Jan. 10, 2005) - SyChip, the leader in Radio Frequency Chip Scale Modules/System in Package (CSM/SIP) modules, today announced its Integrated Passive Device (IPD) technology as a means for developing miniature products for the mobile handheld market space, including smart phones, feature phones, PDAs, gaming devices and media players.

"The worldwide adoption of WLAN is continuing at a feverish pace, and the integration of WLAN into portable devices is at the forefront this trend," said Moses Asom, co-founder and senior vice president of marketing and business development, SyChip. "As the trend to push the network edge into these devices continues to drive consumer demand, SyChip's IPD technology, with its world class size, electrical performance and plug-and-play capability, is perfectly positioned to meet the market challenges and help manufacturers reduce design cycles by six months."

SyChip's proprietary IPD technology enables a best-in-class footprint that is crucial to the handheld device market. A complete 802.11g module is realized in an area of 90 square millimeters and a height of only 0.9mm. The technology enables the integration of approximately 50 passive components, such as capacitors, filters, and inductors, directly into the IPD substrate, providing enhanced performance along with a large reduction in discrete components. Performance enhancements are realized by minimizing component and trace parasitic effects while minimizing passive losses, resulting in excellent range. Fewer discrete components lead to reduced assembly time and cost.

SyChip's IPD technology also incorporates the silicon chip-set, including baseband/MAC, EEPROM, and Transceiver. The module comes in a ball grid array (BGA) structure that allows direct mounting to the main printed circuit board using industry standard surface mount technology for high volume production.

About SyChip, Inc.

SyChip designs, develops and markets Radio Frequency Integrated Circuits and Chip Scale Modules for the wireless mobile market. The company focuses on developing RF modules that are differentiated due to proprietary integration, modular architectures, and low loss Silicon technologies. As a result of the proprietary integration, world-class RF system design, proprietary multifunction ASICs, software and smart utilities, SyChip's RF designs drastically reduce component count, offer very small footprints and are easy to integrate into a mobile device. Customers benefit by significantly reducing their time-to-market, increasing performance and improving reliability of their wireless devices. In 2003 SyChip was awarded "Start-Up to Watch" by the Fabless Semiconductor Association (FSA), as well as being selected as Investors' Choice award winner at VentureWire's annual MicroVentures conference.

For more information about SyChip, please visit <http://www.sychip.com>.

###